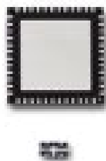
Packaging Availability

MLP



Available in QUAD (MLPQ) and DUAL (MLPD) using saw or punch singulation technologies. Body sizes range from less than 1x1 mm to 9x9 mm with the nominal thickness ranging from 0.5mm to 0.9mm. Lead counts range from 2 to 64 in pitches between 0.4 mm to 1.27 mm and custom sizes are available upon request. Optically clear mold compound options are also available.

SiP

System in Package: Custom array packages with multiple ICs (flip-chip, wire bond, stacked die) and passive components in a single package.

Array

Array options in SSBGA (Organic-BT), SSLGA (BT), and CBGA (Ceramic) are available with various I/O counts in body sizes from 2 x 2 to 17 x 17 mm, and pitches from 0.5 to 1.0 mm using wire bond or flip-chip.

QFP

MQFP
10 x 10.... 24/44/52L
14 x 14.... 64/80L
14 x 20.... 64/80L
14 x 20.... 100/128L

LQFP (1.4 mm)
5 x 5........ 32L
7 x 7........ 32/48/64L
10 x 10.... 44/52/64L
14 x 14.... 64/80/100/120/128L
20 x 20.... 144L
24 x 24.... 176L

TQFP (1 mm)
5 x 5........ 32L
7 x 7........ 32/48L
10 x 10.... 44/64L

Note: some packages are available with bottom of the die attach pad exposed.

SOPs

QSOP (150 mils)
16/20/24/28L

QSOP (300 mils)
36/44L

SOIC(N)
150mils
8/14/16L

SSOP (5.3 mm)
20/24/28L

MSOP (3.0 mm)
8/10L

SOIC(W)
300mils
16/18/20/24/28L

TSSOP (4.4 mm)
8/14/16/20/24/28/38L

TSSOP (6.1 mm)
48/56L

Note: some packages are available with bottom of the die attach pad exposed.

Micro & Power

MICRO

T092		SOT143	4L
SOD323	2L	SOT23	3/5/6/8L
SC79	2L	TSOT	5/6/8L
SOT66x	5/6L	SC70	3/4/5/6/8L

POWER

T0220	3/5/7L
DDPAK	3/5/7L
S-PAK™	3/5/7L
SOT223	4L

PLCC

28/32/44/68

PDIP

300 mils
8/14/16/24L

600 mils
48L

We also offer full turn key wafer probe and final test services using RF, Mixed Signal and Digital testers for all packages. Many products are also available in FCOL™ (Flip Chip On Leadframe) and COL (Chip On Lead). For more information call any of our local Sales Offices, or e-mail info@carsem.com, or visit our web site.

Malaysia
Ipoh (M-site)
tel: 60-5-3123333
fax: 60-5-3125333

Malaysia
Ipoh (S-site)
tel: 60-5-5262333
fax: 60-5-5265333

China
Suzhou
tel: 86-512-6258-8883
fax: 86-512-6258-8885

Europe
UK
tel: 44-1793-853888
fax: 44-1793-855388

USA
Silicon Valley
tel: 831-438-6861
fax: 831-438-6863

USA
Los Angeles
tel: 626-854-0939
fax: 626-854-9139

USA
Dallas
tel: 972-580-1706
fax: 972-580-1806

USA
Boston
tel: 508-699-4720
fax: 508-699-4512

Taiwan
Taichung
tel: 886-917-210285

www.carsem.com
info@carsem.com

A Member of
the Hong Leong Group Malaysia

REV B 03/05